

Specification for Approval

Date: 2021/08/16

Customer:	天诚科技
TAI-TECH P/N:	HSF1210F2SF-900T02
CUSTOMER P/N:	
DESCRIPTION:	
QUANTITY:	

REMARK:										
	Cu	stome	er App	prova	l Fee	edba	ck			
	JL \$\frac{1}{2}		1/2	-t- UT	<i>I</i> /S		<i>17</i> 1=1	<i>N</i> =		

西北臺慶科技股份有限公司 TAI-TECH Advanced Electronics Co.. Ltd

Sales

_ 代理商:

深圳市天**诚**科技有限公司 Shenzhen TsaSun Technology Co., Ltd. Room 209, 2/F, Block A, Tengfei Industrial Building, No.6, Taohua Road, Futian District, Shenzhen TEL: 0755-8335 8885 / 0755-8335 9885 E-mail: sales@tsasun.com www.tsacoil.com

□西北臺慶科技股份有限公司	司
---------------	---

TAI-TECH Advanced Electronics Co., Ltd <u>Headquarter:</u>
NO.1 YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN HSIEN, TAIWAN, R.O.C.
TEL: +886-3-4641148 FAX: +886-3-4643565 http://www.tai-tech.com.tw
E-mail: sales@tai-tech.com.tw

□ 臺慶精密電子(昆山)有限公司

TAI-TECH ADVANCED ELECTRONICS(KUNSHAN) CO., LTD SHINWHA ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA

TEL: +86-512-57619396 FAX: +86-512-57619688

E-mail: hui@tai-tech.com.tw

Sales Dep.

APPROVED	CHECKED
夏暁曼	夏暁曼

R&D Center

APPROVED	CHECKED	DRAWN
羅宜春	梁周虎	卜文娟

Wire Wound Type Common Mode Filter

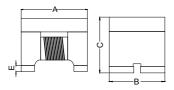
HSF1210F2SF-900T02

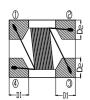
1. Features

1. High common mode impedance at high frequency cause excellent noise suppression performance.

- 2. HSF1210F2SF series realizes small size and low profile. 1.2x1.0x0.9 mm.
- 3. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
- 4. Excellent for USB3.0
- 5. Operating temperature -40~+125 $^{\circ}$ C (Including self temperature rise)

2. Dimension





Series	A(mm)	B(mm)	C(mm)	D1(mm)	D2(mm)	E(mm)
1210F2SF	1.2±0.2	1.0±0.2	0.9 max.	0.35±0.1	0.35±0.1	0.03 min.

3. Part Numbering



A: Series

B: Dimension

C: Material Ferrite
D: Number of Lines 2=2 lines

E: Type S=One Circuit Type , N=Unshielded

F: Lead free

G: Impedance $900=90 \Omega$

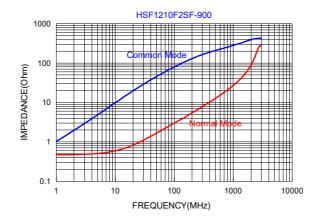
H: Packaging T=Taping and Reel, B=Bulk

I: Rated Current 02=200mA

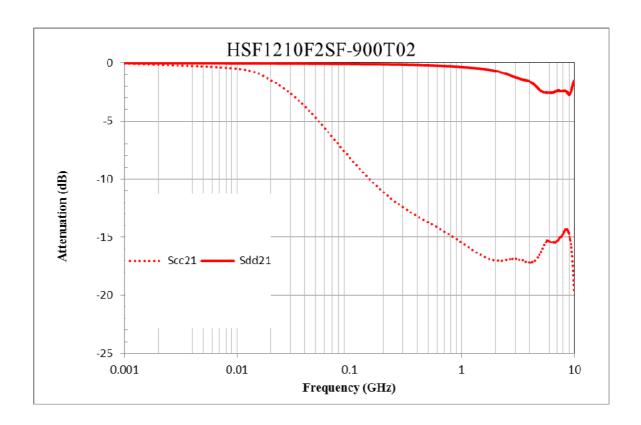
4. Specification

TAI-TECH Part Number	Common mode Impedance (Ω)	Test Frequency (MHz)	DC Resistance (Ω) max.	Rated Current (mA)	Rated Volt. (Vdc)	Withstand Volt. (Vdc)	IR (Ω) min.
HSF1210F2SF-900T02	90±25%	100	0.40	200	50	125	10M

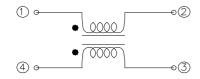




Sdd21&Scc21

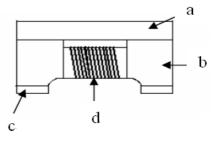


5. Schematic Diagram



6. Materials

No.	Description	Specification
a.	Upper Plate	Ferrite
b.	Core	Ferrite Core
С	Termination	Ag/Ni/Sn
d	Wire	Enameled Copper Wire



7. Reliability and Test Condition

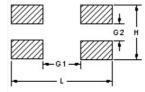
Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	-40~+125℃ (on board)	
Electrical Performance	Test	<u> </u>
Z(common mode)		Agilent-4291A+ Agilent -16197A
DCR	Refer to standard electrical characteristics list.	Agilent-4338B
I.R.		Agilent4339
Temperature Rise Test	Rated Current ∆T 40°C Max	Applied the allowed DC current. Temperature measured by digital surface thermometer.
Reliability Test		
Life Test		Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles) Temperature: 125±2°C Applied current: rated current Duration: 1000±12hrs Measured at room temperature after placing for 24±2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Humidity: 85±2% R.H, Temperature: 85℃±2℃ Duration: 1000hrs Min. Bead: with 100% rated current Inductance: with 10% rated current Measured at room temperature after placing for 24±2 hrs
Moisture Resistance	Appearance: No damage. Impedance: within±15% of initial value RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles 1. Baked at50°C for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 3. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 4. Keep at 25°C for 2 hrs then keep at -10°C for 3 hrs 4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles Condition for 1 cycle $Step1: -40\pm2^{\circ}C 30\pm5min$ $Step2: 25\pm2^{\circ}C \leqq 0.5min$ $Step3: 125\pm2^{\circ}C 30\pm5min$ $Number of cycles: 500$
Vibration		Measured at room temperature after placing for 24±2 hrs Oscillation Frequency: 10Hz~2KHz~10Hz for 20 minute Equipment: Vibration checker Total Amplitude:10g Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations)

Item	Performance	Test Condition
Bending	Appearance : No damage. Impedance : within±15% of initial value	Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.
Shock	RDC : within ±15% of initial value and shall not exceed the specification value	Type Peak Normal Wave change (g's) (ms) Wave form (Vi)ft/sec
		SMD 50 11 Half-sine 11.3
		Lead 50 11 Half-sine 11.3
Solder ability	More than 95% of the terminal electrode should be covered with solder。	a. Method B, 4 hrs @155°C dry heat @235°C±5°C Testing Time :5 +0/-0.5 seconds b. Method D category 3. (8hours ± 15 min)@ 260°C±5°C Testing Time :30 +0/-0.5 seconds
Resistance to Soldering Heat		Depth: completely cover the termination Temperature(°C) Time(s) Temperature ramp/immersion and emersion rate leat cycles 260 ±5 (solder temp) 10 ±1 25mm/s ±6 mm/s 1
Terminal Strength	Appearance: No damage. Impedance: within±15% of initial value RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 3 times.(IPC/JEDEC J-STD-020E Classification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.

8. Soldering and Mounting

8-1. Recommended PC Board Pattern

	HSF1210F2S
L(mm)	1.55
H(mm)	1.10
G1(mm)	0.65
G2(mm)	0.30



8-2. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

8-2.1 IR Soldering Reflow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. Table 1.1&1.2 (J-STD-020E)

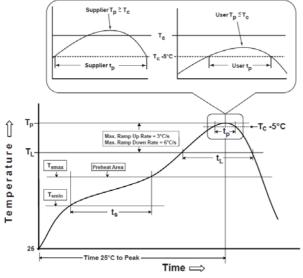
8-2.2 Soldering Iron:

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. (Figure 2.)

- Preheat circuit and products to 150°C
- Never contact the ceramic with the iron tip
- · Use a 20 watt soldering iron with tip diameter of 1.0mm

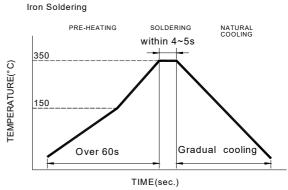
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.

Fig.1 IR Soldering Reflow



Reflow times: 3 times max

Fig.2 Iron soldering temperature profiles



Iron Soldering times: 1 times max

Table (1.1): Reflow Profiles

Profile Type:	Pb-Free Assembly
$eq:total_continuous_cont$	150°C 200°C 60-120seconds
Ramp-up rate(T _L to T _p)	3°ℂ/second max.
Liquidus temperature(T _L) Time(t _L)maintained above T _L	217°C 60-150 seconds
Classification temperature(T _c)	See Table (1.2)
$\label{eq:tp} \mbox{Time}(t_p) \mbox{ at Tc-} \mbox{ 5}^{\circ} \mbox{$^{\circ}$} \mbox{ (Tp should be equal to or less than Tc.)}$	< 30 seconds
Ramp-down rate(T _p to T _L)	6°C /second max.
Time 25°℃ to peak temperature	8 minutes max.

Tp: maximum peak package body temperature, Tc: the classification temperature.

For user (customer) Tp should be equal to or less than Tc.

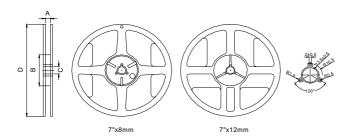
Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package	Volume mm ³	Volume mm ³	Volume mm ³
	Thickness	<350	350-2000	>2000
	<1.6mm	260°C	260°C	260°C
PB-Free Assembly	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E ∘

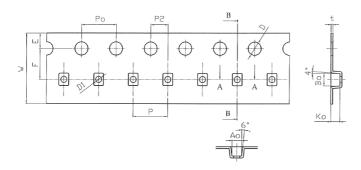
9. Packaging Information

9-1. Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0±0.5	60±2	13.5±0.5	178±2

9-2. Tape Dimension / 8mm

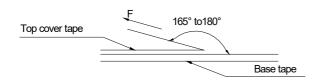


Series	W(mm)	P(mm)	E(mm)	F(mm)	P2(mm)	D(mm)	D1(mm)	P0(mm)	A0(mm)	B0(mm)	K0(mm)	t(mm)
HSF1210F2S	8.00±0.10	4.00±0.10	1.75±0.10	3.50±0.05	2.00±0.05	1.50+0.10/-0.00	0.70±0.10	4.00±0.10	1.12±0.10	1.40±0.10	1.05±0.10	0.22±0.05

9-3. Packaging Quantity

Chip size	Chip/Reel	Inner Box	Middle Box	Carton
HSF1210F2S	3000	15000	75000	150000

9-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity	Room atm	Tearing Speed		
(℃)	(%)	(hPa)	mm/min		
5~35	45~85	860~1060	300		

Application Notice

- Storage Conditions(component level)
 - To maintain the solderability of terminal electrodes:
- 1. TAI-TECH products meet IPC/JEDEC J-STD-020E standard-MSL, level 1.
- 2. Temperature and humidity conditions: Less than 40°C and 60% RH.
- 3. Recommended products should be used within 12 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 - 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
 - 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
 - 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.



Test Report

號碼(No.): CE/2020/33003

日期(Date): 2020/03/19

頁數(Page): 1 of 13

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

(江蘇省昆山市筵朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description)

WIREWOUND SERIES

樣品型號(Style/Item No.)

WCM(YCW) · WCL · HSF · HDMI · DVI · BCM · PCM · TCM · LCM · LPF · TXF · ACM ·

DCM(YLW) · WIH · BPH · TNH · YCM · STF · APO · TLM · SWFS · QLL SERIES

收件日期(Sample Receiving Date)

2020/03/12

測試期間(Testing Period)

2020/03/12 to 2020/03/19

測試結果(Test Results) : 請參閱下一頁 (Please refer to following pages).

Troy Chắng / Manager - Vied Signed for and behalf of SĞS TAIWAN LTD. Chemical Laboratory - Taipei



PIN CODE: C6A74570



Test Report

號碼(No.): CE/2020/33003

日期(Date): 2020/03/19

頁數(Page): 2 of 13

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

(江蘇省昆山市筵朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

測試結果(Test Results)

測試部位(PART NAME)No.1

: 整體混測 (MIXED ALL PARTS)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	MDL	結果 (Result) No.1
鐍 / Cadmium (Cd)	mg/kg	參考IEC 62321-5 (2013),以威應耦合電 漿發射光譜儀檢測. / With reference	2	n, d,
鉛 / Lead (Pb)	mg/kg	to IEC 62321-5 (2013) and performed by ICP-OES.	2	n, d.
汞 / Mercury (Hg)	mg/kg	参考IEC 62321-4:2013+ AMD1:2017,以 感應耦合電漿發射光譜儀檢測. / With reference to IEC 62321-4:2013+ AMD1:2017 and performed by ICP-OES.	2	n. d.
六價鉻 / Hexavalent Chromium Cr(VI)	mg/kg	參考IEC 62321-7-2 (2017),以UV-VIS檢 測. / With reference to IEC 62321-7- 2 (2017) and performed by UV-VIS.	8	n. d.
多溴聯苯總和 / Sum of PBBs	mg/kg			n. d.
一溴聯苯 / Monobromobiphenyl	mg/kg		5	n. d.
二溴聯苯 / Dibromobiphenyl	mg/kg	1	5	n. d.
三溴聯苯 / Tribromobiphenyl	mg/kg	1, ,	5	n. d.
四溴聯苯 / Tetrabromobiphenyl	mg/kg	参考IEC 62321-6 (2015),以氣相層析/	5	n. d.
五溴聯苯 / Pentabromobiphenyl	mg/kg	g譜儀檢測. / With reference to IEC - 62321-6 (2015) and performed by - -GC/MS.	5	n. d.
六溴聯苯 / Hexabromobiphenyl	mg/kg		5	n. d.
七溴聯苯 / Heptabromobiphenyl	mg/kg	700/ MO.	5	n. d.
八溴聯苯 / Octabromobiphenyl	mg/kg]	5	n. d.
九溴聯苯 / Nonabromobiphenyl	mg/kg]	5	n. d.
十溴聯苯 / Decabromobiphenyl	mg/kg]	5	n. d.

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at https://www.sgs.com/en/Terms-and-Conditions.asex and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at https://www.sgs.com/en/Terms-and-conditions/terms-e-document. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approved of the Company, Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the full-lest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2020/33003

日期(Date): 2020/03/19

頁數(Page): 3 of 13

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

(江蘇省昆山市筵朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R., CHINA)

测試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	MDL	結果 (Result)
(lest items)	(01111)	(MC HIOU)		No. 1
多溴聯苯醚總和 / Sum of PBDEs	mg/kg		_	n. d.
一溴聯苯醚 / Monobromodiphenyl ether	mg/kg		5	n. d.
二溴聯苯醚 / Dibromodiphenyl ether	mg/kg		5	n. d.
三溴聯苯醚 / Tribromodiphenyl ether	mg/kg	A & IDO 20001 0 (0015)	5	n. d.
四溴聯苯醚 / Tetrabromodiphenyl ether	mg/kg	参考IEC 62321-6 (2015),以氣相層析/	5	n. d.
五溴聯苯醚 / Pentabromodiphenyl ether	mg/kg	質譜儀檢測,/ With reference to IEC 62321-6 (2015) and performed by	5	n. d.
六溴聯苯醚 / Hexabromodiphenyl ether	mg/kg	GC/MS.	5	n. d.
七溴聯苯醚 / Heptabromodiphenyl ether	mg/kg	10C/ MO.	5	n. d.
八溴聯苯醚 / Octabromodiphenyl ether	mg/kg		5	n. d.
九溴聯苯醚 / Nonabromodiphenyl ether	mg/kg		5	n. d.
十溴聯苯醚 / Decabromodiphenyl ether	mg/kg		5	n. d.
鹵素 / Halogen				
鹵素(氟)/ Halogen-Fluorine (F) (CAS No.: 14762-94-8)	mg/kg		50	n. d.
鹵素 (氣) / Halogen-Chlorine (C1) (CAS No.: 22537-15-1)	mg/kg	参考BS EN 14582 (2016),以離子層析儀 分析. / With reference to BS EN	50	n. d.
鹵素(溴)/ Halogen-Bromine (Br) (CAS No.: 10097-32-2)	mg/kg	14582 (2016). Analysis was performed by IC.	50	n. d.
鹵素(碘)/ Halogen-Iodine(I)(CAS No.: 14362-44-8)	mg/kg]	50	n. d.
全氟辛烷磺酸 / Perfluorooctane sulfonates (PFOS-Acid, Metal Salt, Amide)	mg/kg	参考US EPA 3550C (2007),以液相層析/ 質譜儀檢測. / With reference to US EPA 3550C (2007). Analysis was	10	n, d.
全氟辛酸 / PFOA (CAS No.: 335-67-1)	mg/kg	performed by LC/MS.	10	n. d.

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at https://www.sgs.com/en/Terms-and-Conditions.aspx and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at https://www.sgs.com/en/Terms-and-conditions/terms-e-document. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its indevention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction document. This document cannot be reproduced, except in full, without prior written approved of the Company. Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2020/33003

日期(Date): 2020/03/19

頁數(Page): 4 of 13

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R., CHINA)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	MDL	結果 (Result) No.1
鄰苯二甲酸丁苯甲酯 / BBP (Butyl Benzyl phthalate) (CAS No.: 85-68-7)	mg/kg		50	n. d.
鄰苯二甲酸二丁酯 / DBP (Dibutyl phthalate) (CAS No.: 84-74-2)	mg/kg		50	n. d.
鄰苯二甲酸二 (2-乙基己基)酯 / DEHP (Di- (2-ethylhexyl) phthalate) (CAS No.: 117-81-7)	mg/kg		50	n. d.
鄰苯二甲酸二異丁酯 / DIBP (Di-isobutyl phthalate) (CAS No.: 84-69-5)	mg/kg		50	n. d.
鄰苯二甲酸二異癸酯 / DIDP (Di- isodecyl phthalate) (CAS No.: 26761- 40-0; 68515-49-1)	mg/kg	参考IEC 62321-8 (2017),以氣相層析/ 質譜儀檢測. / With reference to IEC 62321-8 (2017). Analysis was performed by GC/MS.	50	n. d.
鄰苯二甲酸二異壬酯 / DINP (Di- isononyl phthalate) (CAS No.: 28553- 12-0; 68515-48-0)	mg/kg		50	n. d.
鄰苯二甲酸二正辛酯 / DNOP (Di-n- octyl phthalate) (CAS No.: 117-84-0)	mg/kg		50	n. d.
鄰苯二甲酸二正己酯 / DNHP (Di-n-hexyl phthalate) (CAS No.: 84-75-3)	mg/kg		50	n. d.
鄰苯二甲酸二戊酯 / DNPP (Di-n-pentyl phthalate) (CAS No.: 131-18-0)	mg/kg		50	n. d.
六溴環十二烷及所有主要被辨別出的異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified (α - HBCDD, β - HBCDD, γ - HBCDD) (CAS No.: 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8))	mg/kg	参考IEC 62321 (2008),以氣相層析/質 譜儀檢測. / With reference to IEC 62321 (2008). Analysis was performed by GC/MS.	5	n. d.

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.sgs.com/en/Terms-and-Conditions.asex and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at https://www.sgs.com/en/terms-and-conditions/terms-e-document. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company indicates the time of its intervention only and within the limits of client's instruction, in surface, in surface, in any the Company is sole responsibility is to its Client and this document does not exponerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company, Any unauthorized alleration, forgery or fasification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2020/33003

日期(Date): 2020/03/19

頁數(Page): 5 of 13

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺廣精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R., CHINA)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	MDL	結果 (Result) No.1
绨 / Antimony (Sb)	mg/kg	参考US EPA 3052 (1996),以感應耦合電 漿發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-OES.	2	n. d.
鈹 / Beryllium (Be)	mg/kg	参考US EPA 3052 (1996),以威應耦合電 漿發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-OES.	2	п. d.

備註(Note):

- 1. mg/kg = ppm : 0.1wt% = 1000ppm
- 2. MDL = Method Detection Limit (方法偵測極限值)
- 3. n.d. = Not Detected (未檢出)
- 4. "-" = Not Regulated (無規格值)
- 5. 樣品的測試是基於申請人要求混合測試,報告中的混合測試結果不代表其中個別單一材質的含量. (The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)

PFOS参考資訊(Reference Information): 持久性有機污染物 POPs - (EU) 2019/1021

PFOS濃度在物質或製備中不得超過0.001%(10ppm),在半成品、成品或零部件中不得超過0.1%(1000ppm),在紡織品或塗 層材料中不得超過lug/m2。

(Outlawing PFOS as substances or preparations in concentrations above 0.001% (10ppm), in semi-finished products or articles or parts at a level above 0.1%(1000ppm), in textiles or other coated materials above 1µg/m².)

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.ses.com/en/Terms-and-Conditions.ses.x and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at https://www.ses.com/en/terms-and-conditions/terms-e-document.-Attention is advant to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company, Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2020/33003

日期(Date): 2020/03/19

頁數(Page): 6 of 13

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

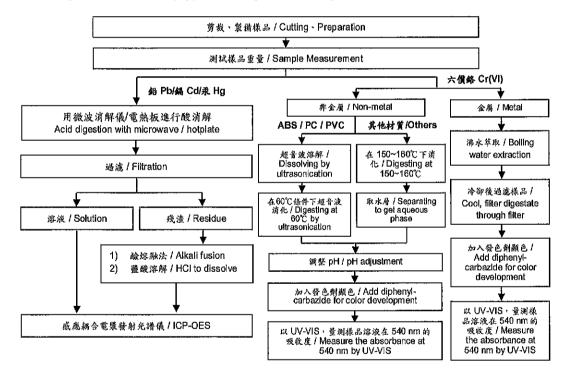
桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

(江蘇省昆山市筵朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R., CHINA)

重金屬流程圖 / Analytical flow chart of Heavy Metal

根據以下的流程圖之條件,樣品已完全溶解。(六價絡測試方法除外)

These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr⁶⁺ test method excluded)



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at https://www.sas.com/en/Terms_and-Conditions.asex and, for electronic formal documents, subject to Terms and Conditions for Electronic Documents at https://www.sas.com/en/Terms-and-conditions/terms-e-document_Attention is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company, Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2020/33003

日期(Date): 2020/03/19

頁數(Page): 7 of 13

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

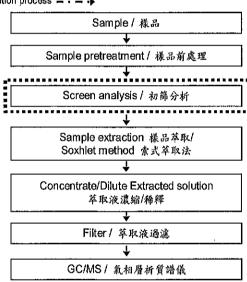
(慶邦電子元器件(泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

(江蘇省昆山市筵朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R., CHINA)

多溴聯苯/多溴聯苯醚分析流程圖 / Analytical flow chart - PBB/PBDE

初次测试程序 / First testing process -確認程序 / Confirmation process - - - →



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.sgs.com/en/Terms-ard-Conditions.asex and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at <a href="https://www.sgs.com/en/terms-ard-conditions/terms-e-document_Attention is drawn to the limitation of liability, Indamnification and Jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company, any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2020/33003

日期(Date): 2020/03/19

頁數(Page): 8 of 13

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

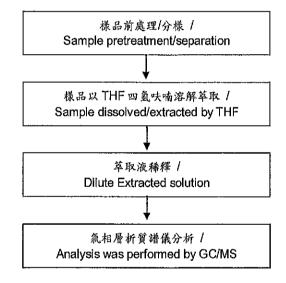
(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

(江蘇省昆山市筵朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R., CHINA)

可塑劑分析流程圖 / Analytical flow chart - Phthalate

【测試方法/Test method: IEC 62321-8】



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <a href="https://www.sgs.com/en/Terms-and-Conditions/terms



Test Report

號碼(No.): CE/2020/33003

日期(Date): 2020/03/19

頁數(Page): 9 of 13

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

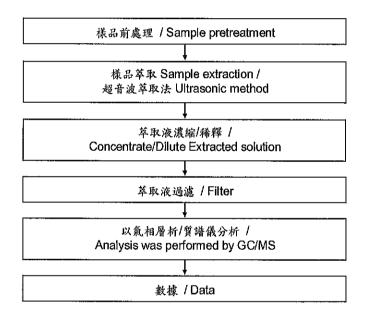
(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

六溴環十二烷分析流程圖 / Analytical flow chart - HBCDD



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.sas.com/en/Terms-and-Conditions for electronic Documents at https://www.sas.com/en/terms-and-conditions/terms-e-document. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that Information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company, any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2020/33003

日期(Date): 2020/03/19

頁數(Page): 10 of 13

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

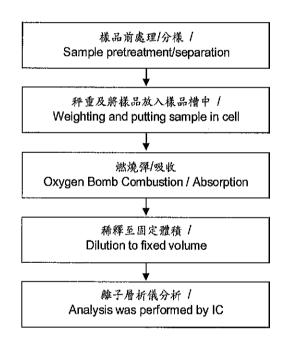
(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

鹵素分析流程圖 / Analytical flow chart - Halogen



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at https://www.sgs.com/eng-terms-and-Conditions-asex and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at https://www.sgs.com/en/terms-and-conditions/terms-e-document. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company, Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unfawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2020/33003

日期(Date): 2020/03/19

頁數(Page): 11 of 13

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

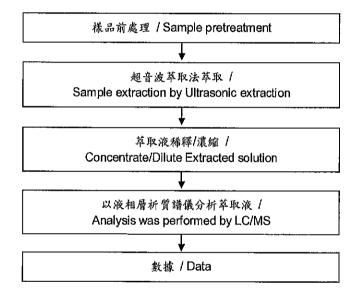
(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN,

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R., CHINA)

全氯辛酸/全氯辛烷磺酸分析流程圖 / Analytical flow chart - PFOA/PFOS



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.sgs.com/en/Terms-and-Conditions-asex and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at https://www.sgs.com/en/terms-and-conditions/terms-e-document. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction document. This document cannot be reproduced, except in full, without prior written approval of the Company, Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2020/33003

日期(Date): 2020/03/19

頁數(Page): 12 of 13

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

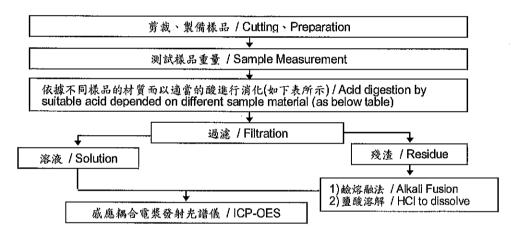
(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD,KUNJIA HI-TECH INDUSTRIAL PARK,KUN-SHAN,JIANG-SU,CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R., CHINA)

元素以 ICP-OES 分析的消化流程圖 (Flow Chart of digestion for the elements analysis performed by ICP-OES)

根據以下的流程圖之條件,樣品已完全溶解。 / These samples were dissolved totally by pre-conditioning method according to below flow chart.



鲷,銅,鋁,焊錫 / Steel, copper, aluminum, solder	王水,硝酸,鹽酸,氫氟酸,雙氧水 / Aqua regia, HNO ₃ , HCl, HF, H ₂ O ₂
玻璃 / Glass	磷酸,氫氟酸 / HNO ₃ /HF
金,鉑,鲍,陶瓷 / Gold, platinum, palladium, ceramic	王水 / Aqua regia
銀 / Silver	硝酸 / HNO ₃
塑膠 / Plastic	硫酸,雙氧水,硝酸,鹽酸 / H2SO4, H2O2, HNO3, HCI
其他 / Others	加入適當的試劑至完全溶解 / Added appropriate
	reagent to total digestion

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.sgs.com/en/Terms-and-Conditions.asex and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at https://www.sgs.com/en/terms-and-conditions/terms-e-document_Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained herein reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company. Any unauthorized attention, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2020/33003 日期(Date): 2020/03/19 頁數(Page): 13 of 13

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

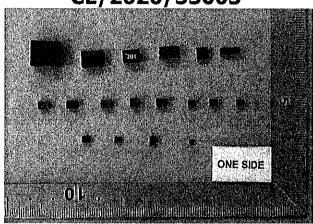
(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

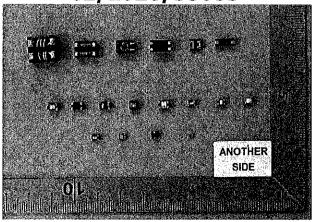
(江蘇省昆山市筵朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

> * 照片中如有箭頭標示,則表示為實際檢測之樣品/部位. * (The tested sample / part is marked by an arrow if it's shown on the photo.)

CE/2020/33003



CE/2020/33003



** 報告結尾 (End of Report) **

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.sgs.com/en/Terms-and-Conditions of Service printed overleaf, available on request or accessible at https://www.sgs.com/en/terms-and-conditions/serms-e-document./, Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the lime of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction document. This document cannot be reproduced, except in full, without prior written approval of the Company, Any unauthorized attention, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.